

WHAT IS CLAIMED IS:

1. A test method of internal connections between a first integrated circuit and a second integrated circuit, both of which are housed in a semiconductor package and connected with each other, comprising:

- 5       applying a test signal to a first pin of the semiconductor package;  
          applying the test signal from the first pin to the first integrated circuit;  
          applying a first signal generated in the first integrated circuit from the test signal to  
the second integrated circuit;  
          applying a second signal generated in the second integrated circuit from the first  
10    signal to the first integrated circuit;  
          outputting a third signal generated in the first integrated circuit from the second  
signal to a second pin of the semiconductor package; and  
          verifying the third signal outputted to the second pin of the semiconductor package.

- 15       2. The test method of claim 1, wherein the first integrated circuit comprises a  
TV signal processing IC which demodulates a TV signal.

3. The test method of claim 2, wherein the second integrated circuit comprises a  
microcomputer which has a function to decode a signal from the TV signal processing IC.

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4. The test method of claim 3, wherein the test signal comprises a closed caption  
signal.

5. The test method of claim 4, wherein the signal outputted to the second pin  
25    comprises one of three primary color signals selected by a switch provided in the first  
integrated circuit between three primary color signals to display a normal picture and  
three primary color signals to display a subtitle.

6. The test method of claim 3, wherein the test signal comprises a video signal  
30    comprising a closed caption signal.